**Absolute Maximum Ratings at Ta=25℃**

| Parameter | MAX. | Unit |
|---|---|---|
| Power Dissipation | 100 | mW |
| Continuous Forward Current | 50 | mA |
| Peak Forward Current *3 | 500 | mA |
| Reverse Voltage | 5 | V |
| Operating Temperature | -40 to + 85 | |
| Storage Temperature | -40 to + 100 | |
| IR Reflow Temperature*4 | 220 for 10 Seconds | |

**1. Storage**

The storage ambient for the LEDs should not exceed 30 ℃ temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

**2. Precautions in handling:**

- When soldering, leave 2mm of minimum clearance from the resin to the soldering point.
- Dipping the resin to solder must be avoided.
- Correcting the soldered position after soldering must be avoided.
- In soldering, do not apply any stress to the lead frame particularly when heated.
- When forming a lead, make sure not to apply any stress inside the resin.
- Lead forming must be done before soldering.
- It is necessary to cut the lead frame at normal temperature.

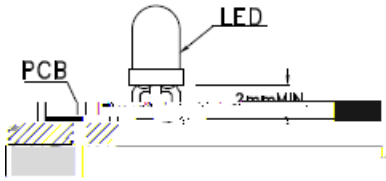
**3. Peak Forward Current:**

Condition for is IFP pulse duty

**Typical Electrical / Optical Characteristics Curves**
**(25℃ Ambient Temperature Unless Otherwise Noted)**

## LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend (Fig.5 and Fig.6).




ig. 5

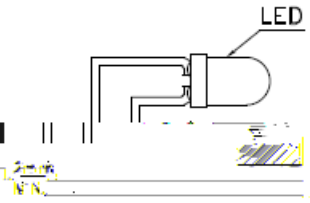



Fig. 6 F

2. Lead forming or bending must be performed before soldering, never during or after soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB (Fig.7).
5. Do not bend the leads more than twice(Fig.8)

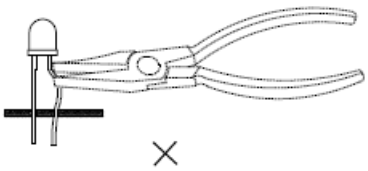


Fig. 7

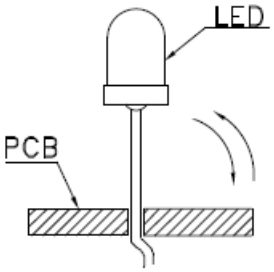



Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50 before applying force (Fig.9).In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with LIGHT representative for proper handling procedures.

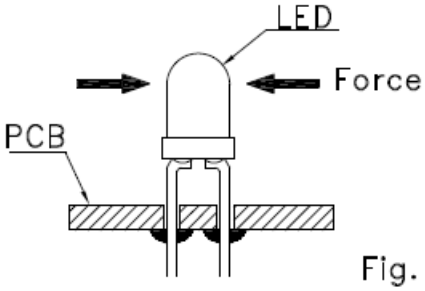



Fig. 9